压差、补偿压力传感器（0至40千帕）

MPX230xDT1

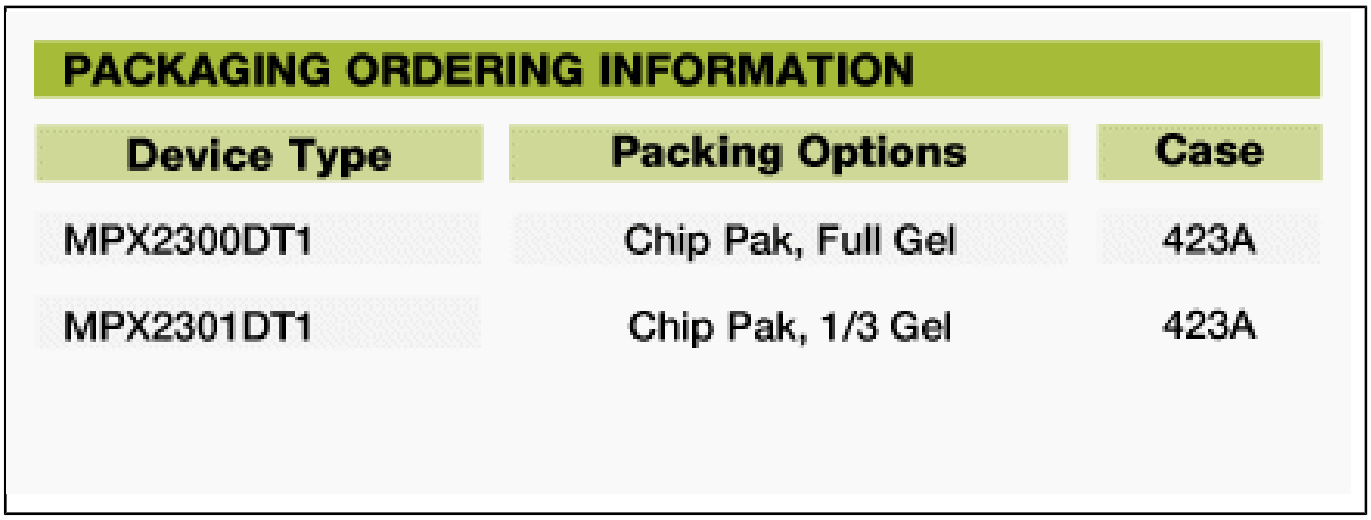
Last Updated: Aug 4, 2026

自2026年2 月2日起，恩智浦MEMS传感器产品已转移至意法半导体。如需更多信息，请联系意法半导体。

MPX230xDT1提供一个高性价比、大量程微型压力传感器封装产品，适用于医疗应用。

- 它是子模块组件或一次性使用元件的理想解决方案
- 采用了我们带压阻技术的传感器晶片，同时添加了片上薄膜温度补偿及校准功能
- 降低了系统设计成本，提高了灵活性

MPX230XDT1_BD Block Diagram



PACKAGING ORDERING INFORMATION

Device Type	Packing Options	Case
MPX2300DT1	Chip Pak, Full Gel	423A
MPX2301DT1	Chip Pak, 1/3 Gel	423A

View additional information for 压差、补偿压力传感器（0至40千帕）.

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